



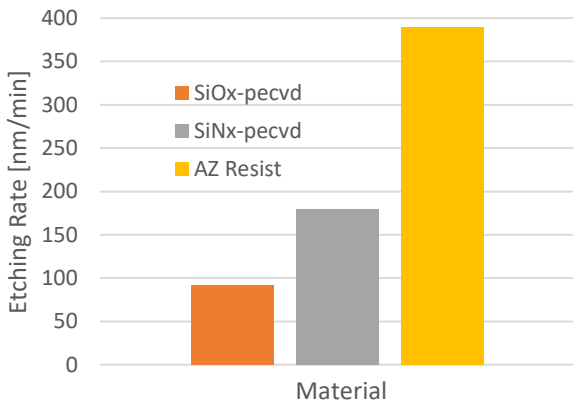
March Etch/Ashing Tool

Nordson March CS-1701 is a reactive ion etching (RIE) system that is excellent for silicide etching and anisotropic etching of nitrides, oxides and polyimides.

Key Features:

- Anisotropic Etching
- Horizontal sample placement
- Single 6" wafer capability, or several smaller pieces.
- Silicon, III-V, glass, metal substrates may be run
- Rough Vacuum – Fast Pumpdown / Vent times
- RF Power 20-400W
- Water Cooled Platen
- Gases : CF₄, O₂, Ar
- NOTE : Manual Operation Required – ON/Off of Vacuum, Gases, Plasma

Etching Rate @250mT, 200W



* Basic Etch recipes have been developed for SiOx and SiNx PECVD films, and Photoresist (Ashing)



- Cover opened showing ~ 6" diameter holding area



- Gas Valves/MFCs and Pressure Gauge